

**FMMT491**  
Rev.G Jan.-201

**描述 / Descriptions**

SOT-23          NPN          Silicon NPN transistor in a SOT-23 Plastic Package.

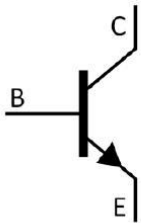
**特征 / Features**

FMMT591  
low equivalent On-resistance, Complementary pair with FMMT591, HF Product.

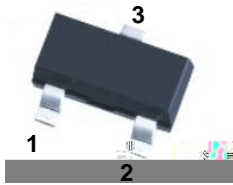
**用途 / Applications**

Medium power amplifier applications.

**内部等效电路 / Equivalent Circuit**



**引脚排列 / Pinning**



PIN1 Base          PIN 2 Emitter          PIN 3 Collector

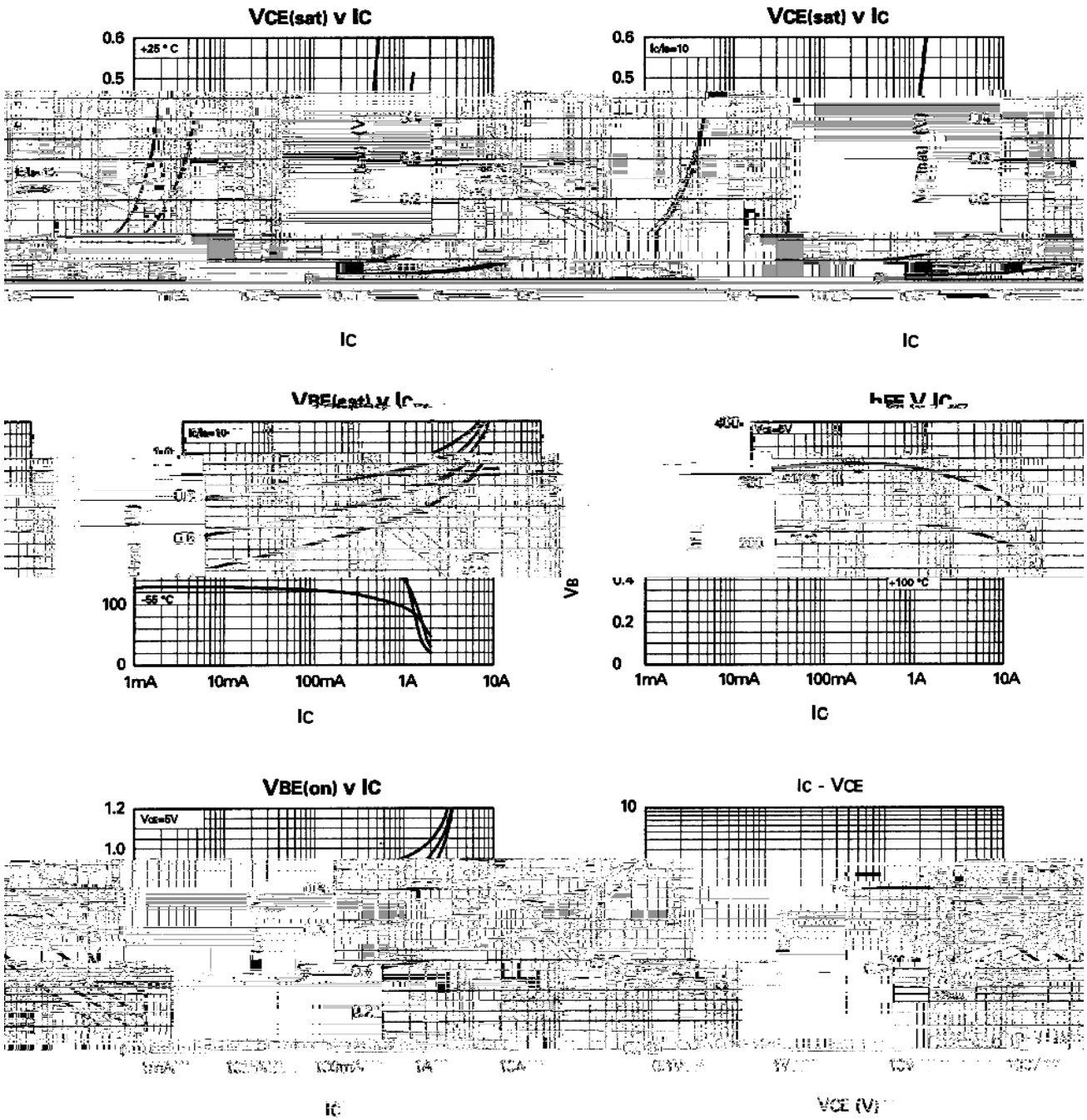
**印章代码 / Marking**

$h_{FE}$ Range	100~300
Marking	H491

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	80	V
Collector to Emitter Voltage	$V_{CEO}$	60	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current - Continuous	$I_C$	1.0	A
Peak Pluse Current	$I_{CM}$	2.0	A
Collector Power Dissipation	$P_C$	500	mW
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

Parameter                      Symbol                      Test Conditions

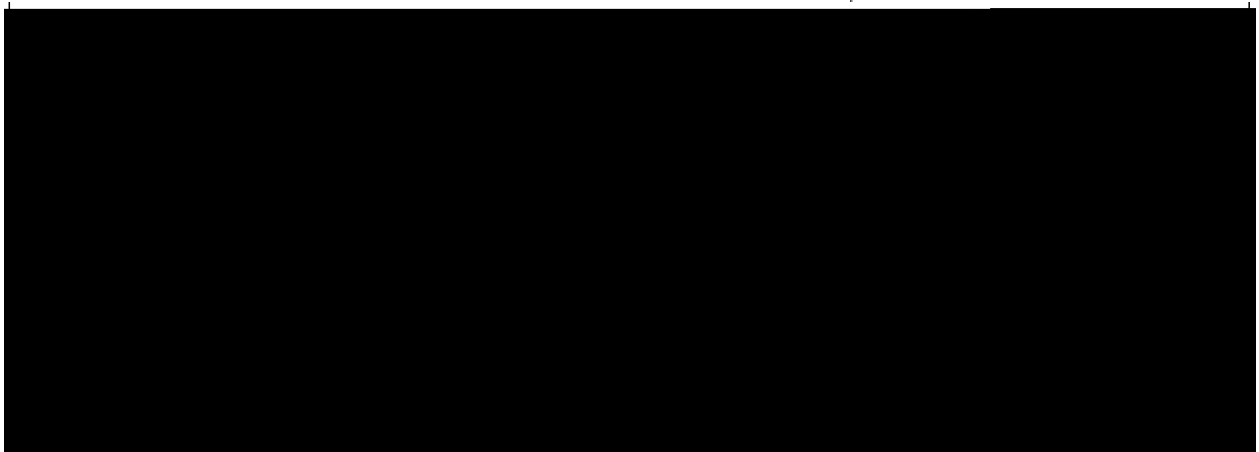
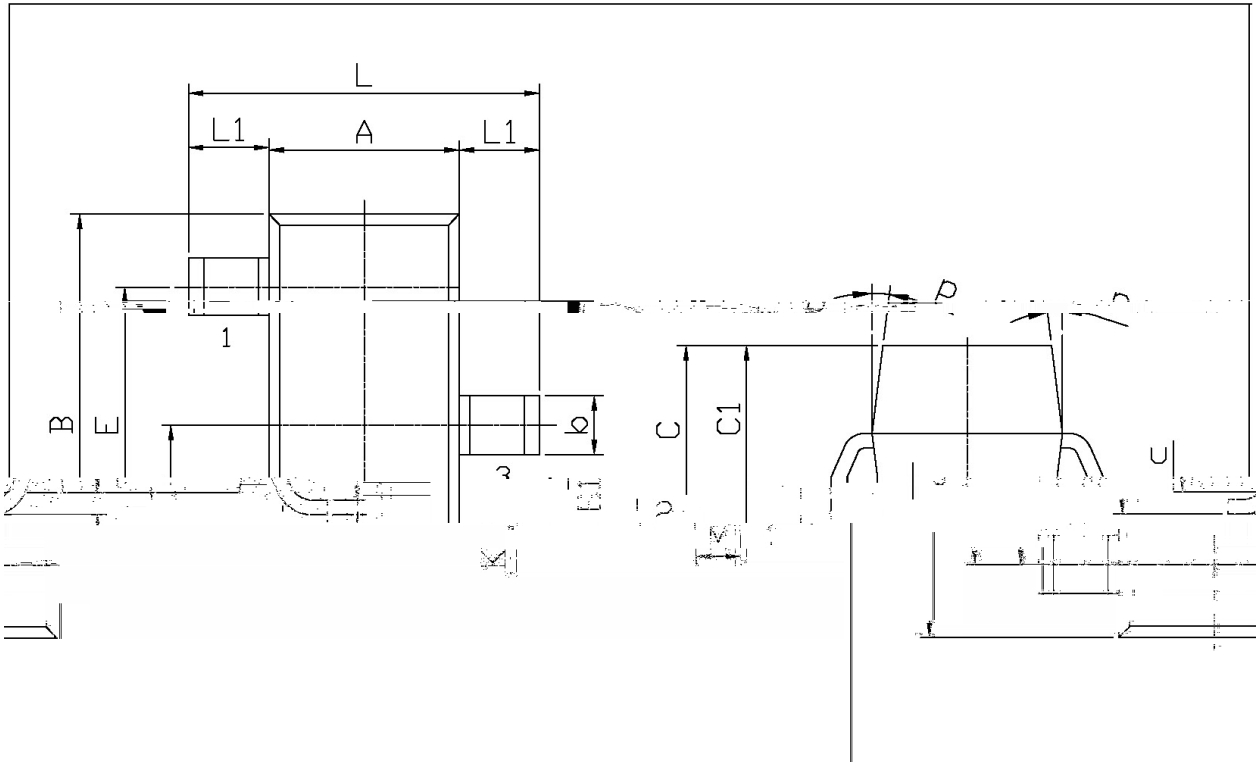
电参数曲线图 / Electrical Characteristic Curve



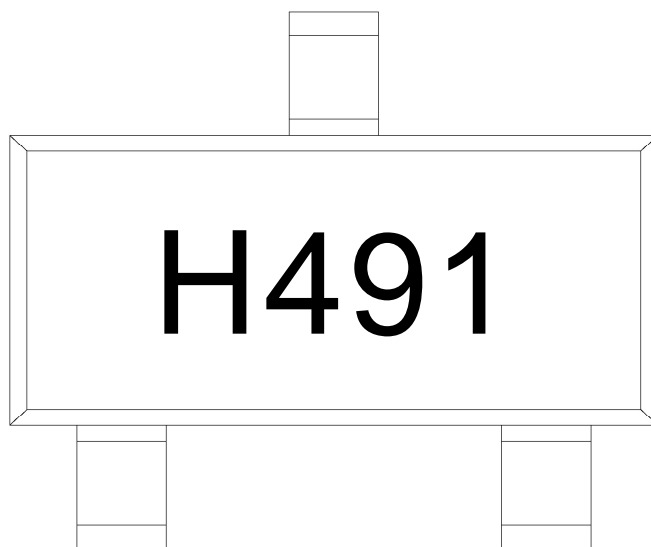
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



H

491

Note:

H: Company Code.

491: Product Type Code.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


Note:

- |   |         |           |  |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec.   |
| 2 | 245±5   | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2       | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec.            |

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

260±5°C                      10±1 sec.                      Temp.:260±5°C                      Time:10±1 sec

**包装规格 / Packaging SPEC.**

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205